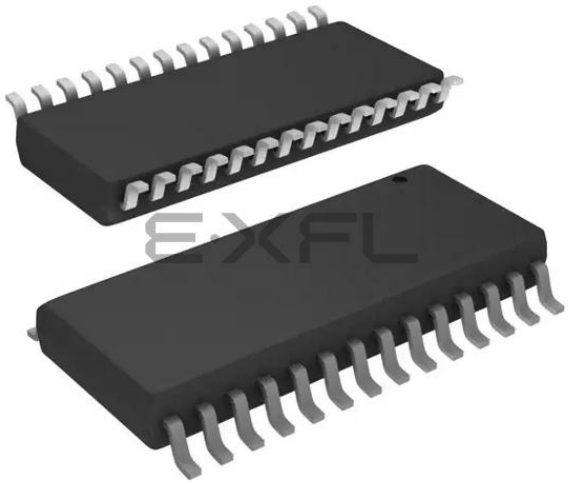

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	30 MIPs
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, QEI, POR, PWM, WDT
Number of I/O	20
Program Memory Size	24KB (8K x 24)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f3010-30i-so

5.1 Interrupt Priority

The user-assignable Interrupt Priority (IP<2:0>) bits for each individual interrupt source are located in the 3 LSbs of each nibble, within the IPCx register(s). Bit 3 of each nibble is not used and is read as a '0'. These bits define the priority level assigned to a particular interrupt by the user.

Note: The user-assignable priority levels start at 0, as the lowest priority, and Level 7, as the highest priority.

Since more than one interrupt request source may be assigned to a specific user-assigned priority level, a means is provided to assign priority within a given level. This method is called "Natural Order Priority".

Natural Order Priority is determined by the position of an interrupt in the vector table, and only affects interrupt operation when multiple interrupts with the same user-assigned priority become pending at the same time.

Table 5-1 lists the interrupt numbers and interrupt sources for the dsPIC DSC devices and their associated vector numbers.

Note 1: The natural order priority scheme has 0 as the highest priority and 53 as the lowest priority.

2: The natural order priority number is the same as the INT number.

The ability for the user to assign every interrupt to one of seven priority levels implies that the user can assign a very high overall priority level to an interrupt with a low natural order priority. For example, the PWM Fault A Interrupt can be given a priority of 7. The INT0 (external interrupt 0) may be assigned to priority Level 1, thus giving it a very low effective priority.

TABLE 5-1: INTERRUPT VECTOR TABLE

Interrupt Number	Vector Number	Interrupt Source
Highest Natural Order Priority		
0	8	INT0 – External Interrupt 0
1	9	IC1 – Input Capture 1
2	10	OC1 – Output Compare 1
3	11	T1 – Timer1
4	12	IC2 – Input Capture 2
5	13	OC2 – Output Compare 2
6	14	T2 – Timer2
7	15	T3 – Timer3
8	16	SPI1
9	17	U1RX – UART1 Receiver
10	18	U1TX – UART1 Transmitter
11	19	ADC – ADC Convert Done
12	20	NVM – NVM Write Complete
13	21	SI2C – I^2C Slave Interrupt
14	22	MI2C – I^2C Master Interrupt
15	23	Input Change Interrupt
16	24	INT1 – External Interrupt 1
17	25	IC7 – Input Capture 7
18	26	IC8 – Input Capture 8
19	27	OC3 – Output Compare 3(1)
20	28	OC4 – Output Compare 4(1)
21	29	T4 – Timer4
22	30	T5 – Timer5
23	31	INT2 – External Interrupt 2
24	32	U2RX – UART2 Receiver(1)
25	33	U2TX – UART2 Transmitter(1)
26	34	Reserved
27	35	Reserved
28	36	Reserved
29	37	Reserved
30	38	Reserved
31	39	Reserved
32	40	Reserved
33	41	Reserved
34	42	Reserved
35	43	Reserved
36	44	Reserved
37	45	Reserved
38	46	Reserved
39	47	PWM – PWM Period Match
40	48	QEI – QEI Interrupt
41	49	Reserved
42	50	Reserved
43	51	$\overline{\text{FLTA}}$ – PWM Fault A
44	52	Reserved
45-53	53-61	Reserved
Lowest Natural Order Priority		

Note 1: Available on dsPIC30F3011 only

6.4 RTSP Operation

The dsPIC30F Flash program memory is organized into rows and panels. Each row consists of 32 instructions or 96 bytes. Each panel consists of 128 rows or 4K x 24 instructions. RTSP allows the user to erase one row (32 instructions) at a time and to program 32 instructions at one time.

Each panel of program memory contains write latches that hold 32 instructions of programming data. Prior to the actual programming operation, the write data must be loaded into the panel write latches. The data to be programmed into the panel is loaded in sequential order into the write latches; instruction 0, instruction 1, etc. The addresses loaded must always be from an even group of 32 boundary.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of TBLWT instructions to load the write latches. Programming is performed by setting the special bits in the NVMCON register. 32 TBLWTL and four TBLWTH instructions are required to load the 32 instructions.

All of the table write operations are single-word writes (2 instruction cycles), because only the table latches are written.

After the latches are written, a programming operation needs to be initiated to program the data.

The Flash program memory is readable, writable and erasable during normal operation over the entire VDD range.

6.5 RTSP Control Registers

The four SFRs used to read and write the program Flash memory are:

- NVMCON
- NVMADR
- NVMADRU
- NVMKEY

6.5.1 NVMCON REGISTER

The NVMCON register controls which blocks are to be erased, which memory type is to be programmed and the start of the programming cycle.

6.5.2 NVMADR REGISTER

The NVMADR register is used to hold the lower two bytes of the effective address. The NVMADR register captures the EA<15:0> of the last table instruction that has been executed and selects the row to write.

6.5.3 NVMADRU REGISTER

The NVMADRU register is used to hold the upper byte of the effective address. The NVMADRU register captures the EA<23:16> of the last table instruction that has been executed.

6.5.4 NVMKEY REGISTER

NVMKEY is a write-only register that is used for write protection. To start a programming or erase sequence, the user must consecutively write 0x55 and 0xAA to the NVMKEY register. Refer to **Section 6.6 “Programming Operations”** for further details.

Note:	The user can also directly write to the NVMADR and NVMADRU registers to specify a program memory address for erasing or programming.

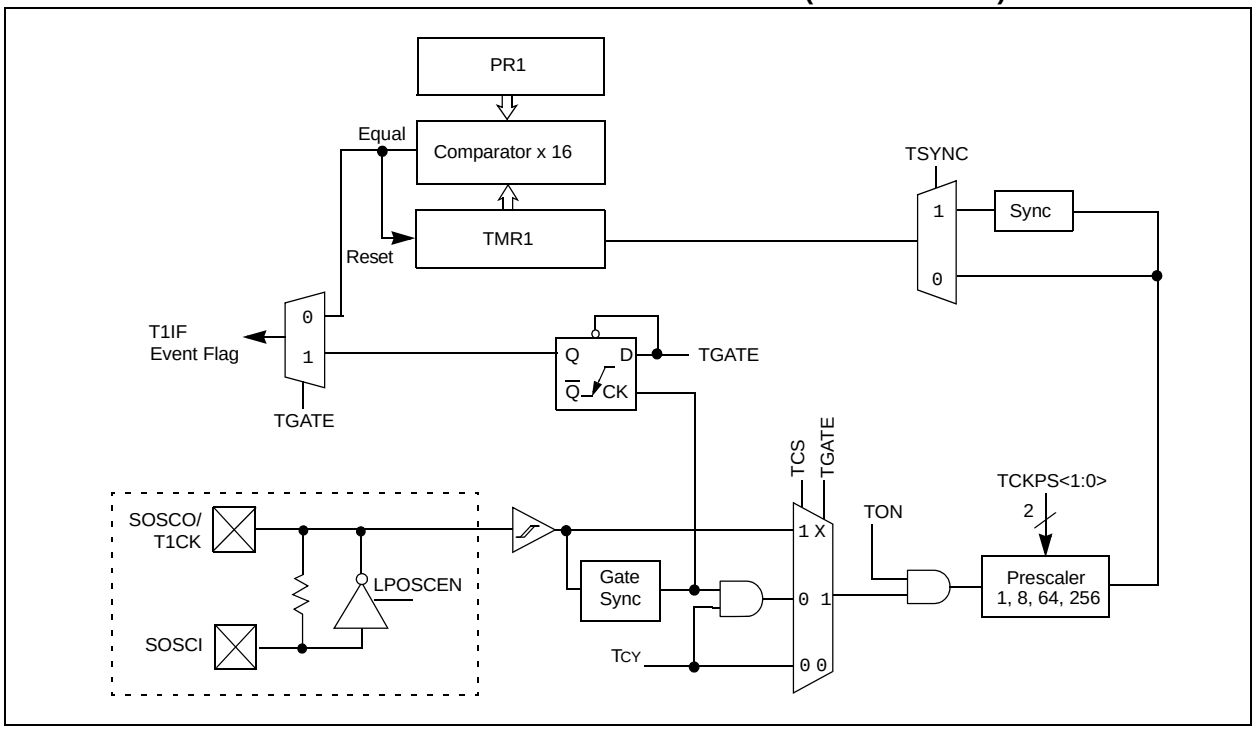
TABLE 6-1: NVM REGISTER MAP(1)

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0760	WR	WREN	WRERR	—	—	—	—	—	—	PROGOP<6:0>							0000 0000 0000 0000
NVMADR	0762	NVMADR<15:0>																uuuu uuuu uuuu uuuu
NVMADRU	0764	—	—	—	—	—	—	—	—	—	NVMADR<22:16>							0000 0000 uuuu uuuu
NVMKEY	0766	—	—	—	—	—	—	—	—	NVMKEY<7:0>								0000 0000 0000 0000

Legend: u = uninitialized bit; — = unimplemented bit, read as '0'

Note 1: Refer to the "*dsPIC30F Family Reference Manual*" (DS70046) for descriptions of register bit fields.

FIGURE 9-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM (TYPE A TIMER)



9.1 Timer Gate Operation

The 16-bit timer can be placed in the Gated Time Accumulation mode. This mode allows the internal TCY to increment the respective timer when the gate input signal (T1CK pin) is asserted high. Control bit, TGATE (T1CON<6>), must be set to enable this mode. The timer must be enabled (TON = 1) and the timer clock source set to internal (TCS = 0).

When the CPU goes into the Idle mode, the timer will stop incrementing unless TSIDL = 0. If TSIDL = 1, the timer will resume the incrementing sequence upon termination of the CPU Idle mode.

9.2 Timer Prescaler

The input clock (FOSC/4 or external clock) to the 16-bit Timer has a prescale option of 1:1, 1:8, 1:64 and 1:256, selected by control bits, TCKPS<1:0> (T1CON<5:4>). The prescaler counter is cleared when any of the following occurs:

- A write to the TMR1 register
- Clearing of the TON bit (T1CON<15>)
- A device Reset such as a POR and BOR

However, if the timer is disabled (TON = 0), then the timer prescaler cannot be reset since the prescaler clock is halted.

The TMR1 register is not cleared when the T1CON register is written. It is cleared by writing to the TMR1 register.

9.3 Timer Operation During Sleep Mode

During CPU Sleep mode, the timer will operate if:

- The timer module is enabled (TON = 1) and
- The timer clock source is selected as external (TCS = 1) and
- The TSYNC bit (T1CON<2>) is asserted to a logic '0', which defines the external clock source as asynchronous

When all three conditions are true, the timer will continue to count up to the Period register and be reset to 0x0000.

When a match between the timer and the Period register occurs, an interrupt can be generated, if the respective timer interrupt enable bit is asserted.

17.12.2 I²C MASTER RECEPTION

Master mode reception is enabled by programming the Receive Enable (RCEN) bit (I2CCON<3>). The I²C module must be Idle before the RCEN bit is set; otherwise, the RCEN bit will be disregarded. The Baud Rate Generator begins counting, and on each rollover, the state of the SCL pin toggles, and data is shifted into the I2CRSR on the rising edge of each clock.

17.12.3 BAUD RATE GENERATOR (BRG)

In I²C Master mode, the reload value for the BRG is located in the I2CBRG register. When the BRG is loaded with this value, the BRG counts down to '0' and stops until another reload has taken place. If clock arbitration is taking place, for instance, the BRG is reloaded when the SCL pin is sampled high.

As per the I²C standard, FSCL may be 100 kHz or 400 kHz. However, the user can specify any baud rate up to 1 MHz. I2CBRG values of '0' or '1' are illegal.

EQUATION 17-1: I2CBRG VALUE

$$I2CBRG = \left(\frac{FCY}{FSCL} - \frac{FCY}{1{,}111{,}111} \right) - 1$$

17.12.4 CLOCK ARBITRATION

Clock arbitration occurs when the master deasserts the SCL pin (SCL allowed to float high) during any receive, transmit or Restart/Stop condition. When the SCL pin is allowed to float high, the Baud Rate Generator is suspended from counting until the SCL pin is actually sampled high. When the SCL pin is sampled high, the Baud Rate Generator is reloaded with the contents of I2CBRG and begins counting. This ensures that the SCL high time will always be at least one BRG rollover count in the event that the clock is held low by an external device.

17.12.5 MULTI-MASTER COMMUNICATION, BUS COLLISION AND BUS ARBITRATION

Multi-master operation support is achieved by bus arbitration. When the master outputs address/data bits onto the SDA pin, arbitration takes place when the master outputs a '1' on SDA, by letting SDA float high while another master asserts a '0'. When the SCL pin floats high, data should be stable. If the expected data on SDA is a '1' and the data sampled on the SDA pin = 0, then a bus collision has taken place. The master will set the MI2CIF pulse and reset the master portion of the I²C port to its Idle state.

If a transmit was in progress when the bus collision occurred, the transmission is halted, the TBF flag is cleared, the SDA and SCL lines are deasserted and a value can now be written to I2CTRN. When the user services the I²C master event Interrupt Service Routine, if the I²C bus is free (i.e., the P bit is set), the user can resume communication by asserting a Start condition.

If a Start, Restart, Stop or Acknowledge condition was in progress when the bus collision occurred, the condition is aborted, the SDA and SCL lines are deasserted and the respective control bits in the I2CCON register are cleared to '0'. When the user services the bus collision Interrupt Service Routine, and if the I²C bus is free, the user can resume communication by asserting a Start condition.

The Master will continue to monitor the SDA and SCL pins, and if a Stop condition occurs, the MI2CIF bit will be set.

A write to the I2CTRN will start the transmission of data at the first data bit, regardless of where the transmitter left off when bus collision occurred.

In a Multi-Master environment, the interrupt generation on the detection of Start and Stop conditions allows the determination of when the bus is free. Control of the I²C bus can be taken when the P bit is set in the I2CSTAT register, or the bus is Idle and the S and P bits are cleared.

17.13 I²C Module Operation During CPU Sleep and Idle Modes

17.13.1 I²C OPERATION DURING CPU SLEEP MODE

When the device enters Sleep mode, all clock sources to the module are shut down and stay at logic '0'. If Sleep occurs in the middle of a transmission, and the state machine is partially into a transmission as the clocks stop, then the transmission is aborted. Similarly, if Sleep occurs in the middle of a reception, then the reception is aborted.

17.13.2 I²C OPERATION DURING CPU IDLE MODE

For the I²C, the I2CSIDL bit selects if the module will stop on Idle or continue on Idle. If I2CSIDL = 0, the module will continue operation on assertion of the Idle mode. If I2CSIDL = 1, the module will stop on Idle.

18.9 Auto Baud Support

To allow the system to determine baud rates of received characters, the input can be optionally linked to a selected capture input. To enable this mode, the user must program the input capture module to detect the falling and rising edges of the Start bit.

18.10 UART Operation During CPU Sleep and Idle Modes

18.10.1 UART OPERATION DURING CPU SLEEP MODE

When the device enters Sleep mode, all clock sources to the module are shut down and stay at logic '0'. If entry into Sleep mode occurs while a transmission is in progress, then the transmission is aborted. The UxTX pin is driven to logic '1'. Similarly, if entry into Sleep mode occurs while a reception is in progress, then the reception is aborted. The UxSTA, UxMODE, Transmit and Receive registers and buffers, and the UxBRG register are not affected by Sleep mode.

If the WAKE bit (UxMODE<7>) is set before the device enters Sleep mode, then a falling edge on the UxRX pin will generate a receive interrupt. The Receive Interrupt Select Mode bit (URXISEL) has no effect for this function. If the receive interrupt is enabled, then this will wake-up the device from Sleep. The UARTEN bit must be set in order to generate a wake-up interrupt.

18.10.2 UART OPERATION DURING CPU IDLE MODE

For the UART, the USIDL bit selects if the module will stop operation when the device enters Idle mode, or whether the module will continue on Idle. If USIDL = 0, the module will continue operation during Idle mode. If USIDL = 1, the module will stop on Idle.

19.7.1.3 1 Msps Configuration Items

The following configuration items are required to achieve a 1 Msps conversion rate.

- Comply with conditions provided in Table 20-2
- Connect external VREF+ and VREF- pins following the recommended circuit shown in Figure 19-2
- Set SSRC<2:0> = 111 in the ADCON1 register to enable the auto-convert option
- Enable automatic sampling by setting the ASAM control bit in the ADCON1 register
- Enable sequential sampling by clearing the SIMSAM bit in the ADCON1 register
- Enable at least two sample and hold channels by writing the CHPS<1:0> control bits in the ADCON2 register
- Write the SMPI<3:0> control bits in the ADCON2 register for the desired number of conversions between interrupts. At a minimum, set SMPI<3:0> = 0001 since at least two sample and hold channels should be enabled
- Configure the A/D clock period to be:

$$\frac{1}{12 \times 1{,}000{,}000} = 83.33 \text{ ns}$$

  by writing to the ADCS<5:0> control bits in the ADCON3 register
- Configure the sampling time to be 2 TAD by writing: SAMC<4:0> = 00010
- Select at least two channels per analog input pin by writing to the ADCHS register

19.7.2 750 ksps CONFIGURATION GUIDELINE

The following configuration items are required to achieve a 750 ksps conversion rate. This configuration assumes that a single analog input is to be sampled.

- Comply with conditions provided in Table 20-2
- Connect external VREF+ and VREF- pins following the recommended circuit shown in Figure 19-2
- Set SSRC<2:0> = 111 in the ADCON1 register to enable the auto-convert option
- Enable automatic sampling by setting the ASAM control bit in the ADCON1 register
- Enable one sample and hold channel by setting CHPS<1:0> = 00 in the ADCON2 register
- Write the SMPI<3:0> control bits in the ADCON2 register for the desired number of conversions between interrupts
- Configure the A/D clock period to be:

$$\frac{1}{(12 + 2) \times 750{,}000} = 95.24 \text{ ns}$$

  by writing to the ADCS<5:0> control bits in the ADCON3 register
- Configure the sampling time to be 2 TAD by writing: SAMC<4:0> = 00010

19.7.3 600 ksps CONFIGURATION GUIDELINE

The configuration for 600 ksps operation is dependent on whether a single input pin is to be sampled or whether multiple pins will be sampled.

19.7.3.1 Single Analog Input

When performing conversions at 600 ksps for a single analog input, at least two sample and hold channels must be enabled. The analog input multiplexer must be configured so that the same input pin is connected to both sample and hold channels. The A/D converts the value held on one S/H channel, while the second S/H channel acquires a new input sample.

19.7.3.2 Multiple Analog Input

The A/D converter can also be used to sample multiple analog inputs using multiple sample and hold channels. In this case, the total 600 ksps conversion rate is divided among the different input signals. For example, four inputs can be sampled at a rate of 150 ksps for each signal or two inputs can be sampled at a rate of 300 ksps for each signal. Sequential sampling must be used in this configuration to allow adequate sampling time on each input.

19.7.3.3 600 ksps Configuration Items

The following configuration items are required to achieve a 600 ksps conversion rate.

- Comply with conditions provided in Table 20-2
- Connect external VREF+ and VREF- pins following the recommended circuit shown in Figure 19-2
- Set SSRC<2:0> = 111 in the ADCON1 register to enable the auto-convert option
- Enable automatic sampling by setting the ASAM control bit in the ADCON1 register
- Enable sequential sampling by clearing the SIMSAM bit in the ADCON1 register
- Enable at least two sample and hold channels by writing the CHPS<1:0> control bits in the ADCON2 register
- Write the SMPI<3:0> control bits in the ADCON2 register for the desired number of conversions between interrupts. At a minimum, set SMPI<3:0> = 0001 since at least two sample and hold channels should be enabled
- Configure the A/D clock period to be:

$$\frac{1}{12 \times 600{,}000} = 138.89 \text{ ns}$$

  by writing to the ADCS<5:0> control bits in the ADCON3 register
- Configure the sampling time to be 2 TAD by writing: SAMC<4:0> = 00010

Select at least two channels per analog input pin by writing to the ADCHS register.

19.13 Configuring Analog Port Pins

The use of the ADPCFG and TRIS registers control the operation of the ADC port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bit set (input). If the TRIS bit is cleared (output), the digital output level (V_{OH} or V_{OL}) will be converted.

The A/D operation is independent of the state of the CH0SA<3:0>/CH0SB<3:0> bits and the TRIS bits.

When reading the PORT register, all pins configured as analog input channels will read as cleared.

Pins configured as digital inputs will not convert an analog input. Analog levels on any pin that is defined as a digital input (including the ANx pins) may cause the input buffer to consume current that exceeds the device specifications.

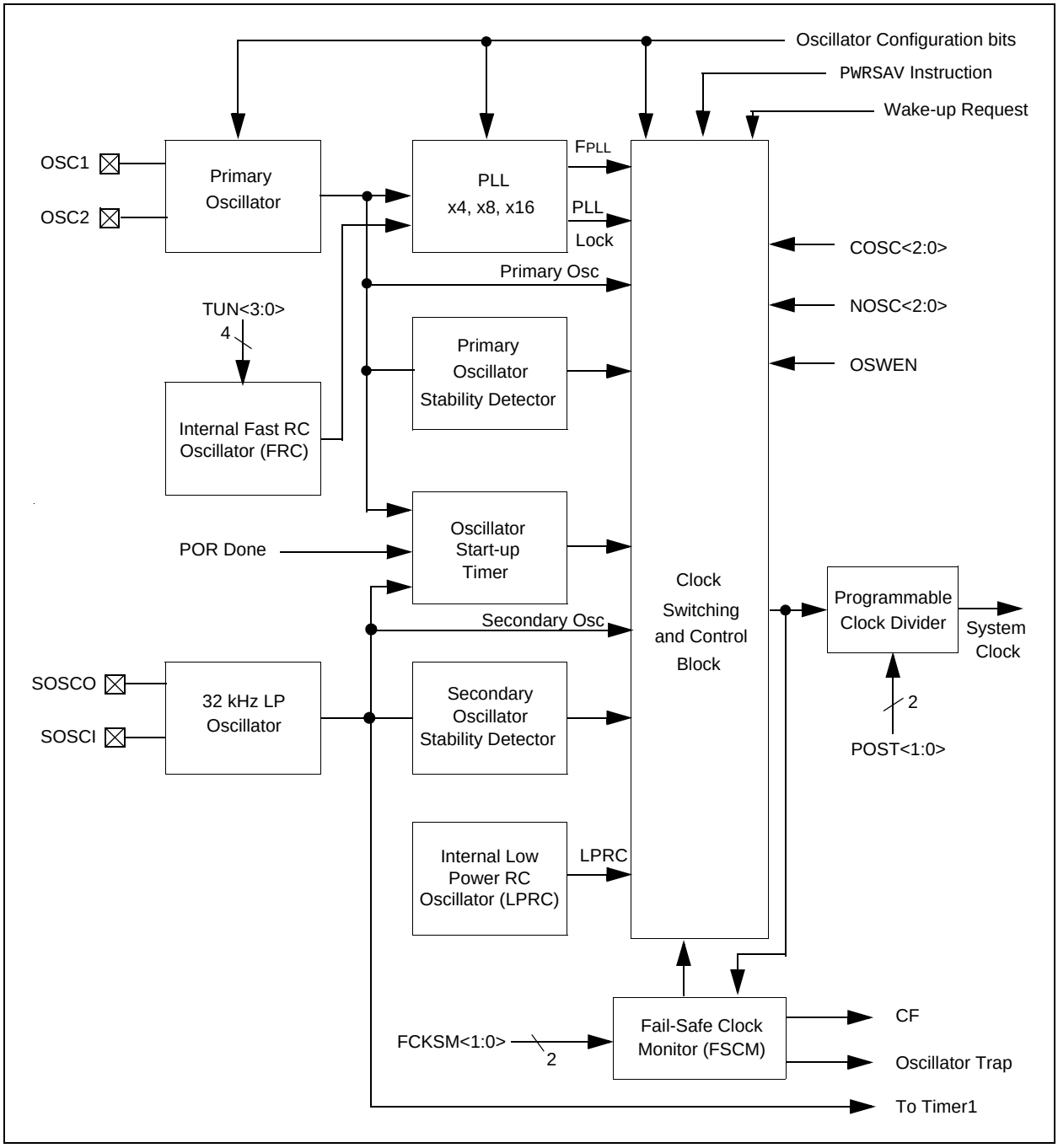
19.14 Connection Considerations

The analog inputs have diodes to V_{DD} and V_{SS} as ESD protection. This requires that the analog input be between V_{DD} and V_{SS}. If the input voltage exceeds this range by greater than 0.3V (either direction), one of the diodes becomes forward biased and it may damage the device if the input current specification is exceeded.

An external RC filter is sometimes added for anti-aliasing of the input signal. The R component should be selected to ensure that the sampling time requirements are satisfied. Any external components connected (via high-impedance) to an analog input pin (capacitor, zener diode, etc.) should have very little leakage current at the pin.

NOTES:

FIGURE 20-1: OSCILLATOR SYSTEM BLOCK DIAGRAM



22.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

22.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

22.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

22.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

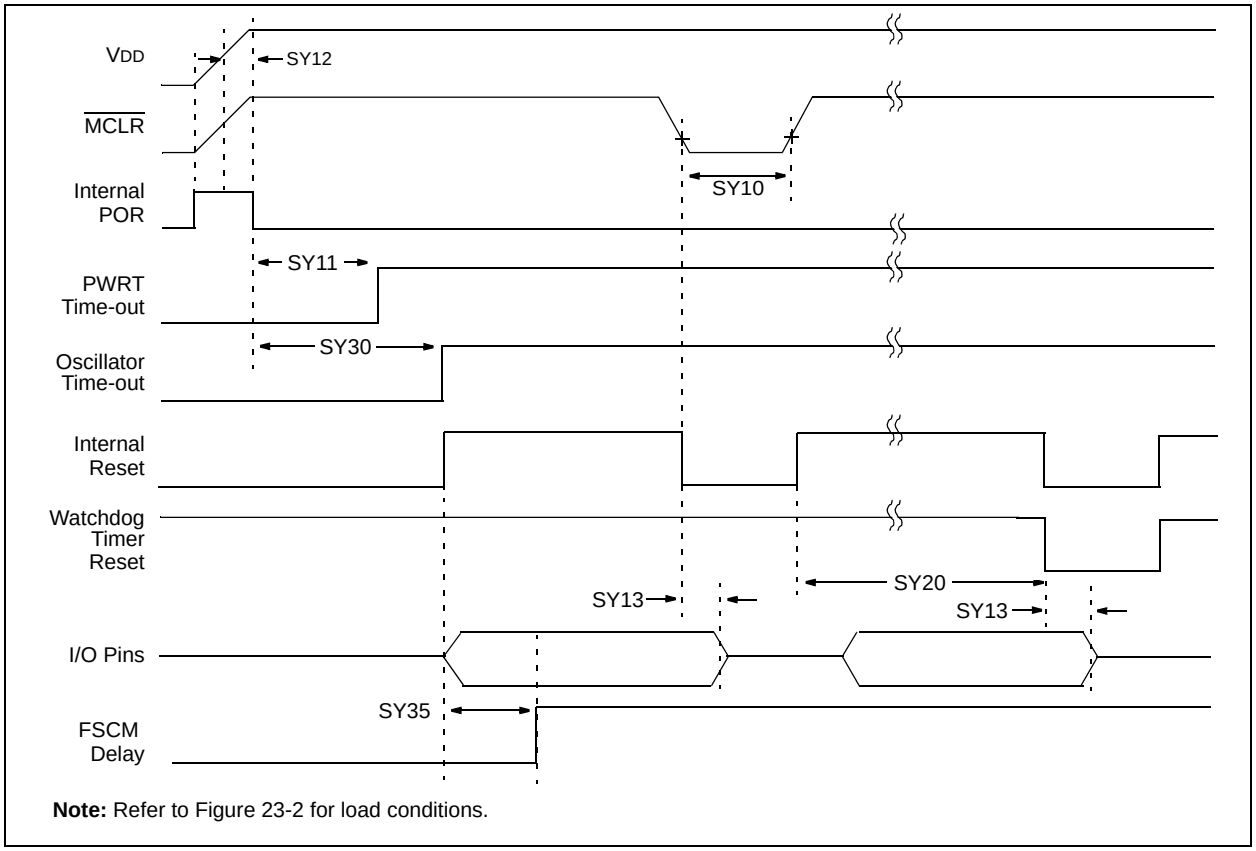
- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

22.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

FIGURE 23-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING CHARACTERISTICS



Note: Refer to Figure 23-2 for load conditions.

TABLE 23-20: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SY10	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	-40°C to +85°C
SY11	TPWRT	Power-up Timer Period	2 10 43	4 16 64	8 32 128	ms	-40°C to +85°C, VDD = 5V User programmable
SY12	TPOR	Power-on Reset Delay	3	10	30	µs	-40°C to +85°C
SY13	TIOZ	I/O High-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	0.8	1.0	µs	
SY20	TWDT1 TWDT2 TWDT3	Watchdog Timer Time-out Period (no prescaler)	1.1 1.2 1.3	2.0 2.0 2.0	6.6 5.0 4.0	ms ms ms	VDD = 2.5V VDD = 3.3V, ±10% VDD = 5V, ±10%
SY25	TBOR	Brown-out Reset Pulse Width(3)	100	—	—	µs	VDD ≤ VBOR (D034)
SY30	TOST	Oscillator Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period

Note 1: These parameters are characterized but not tested in manufacturing.
2: Data in "Typ" column is at 5V, 25°C unless otherwise stated.
3: Refer to Figure 23-1 and Table 23-10 for BOR.

FIGURE 23-14: QEA/QEB INPUT CHARACTERISTICS

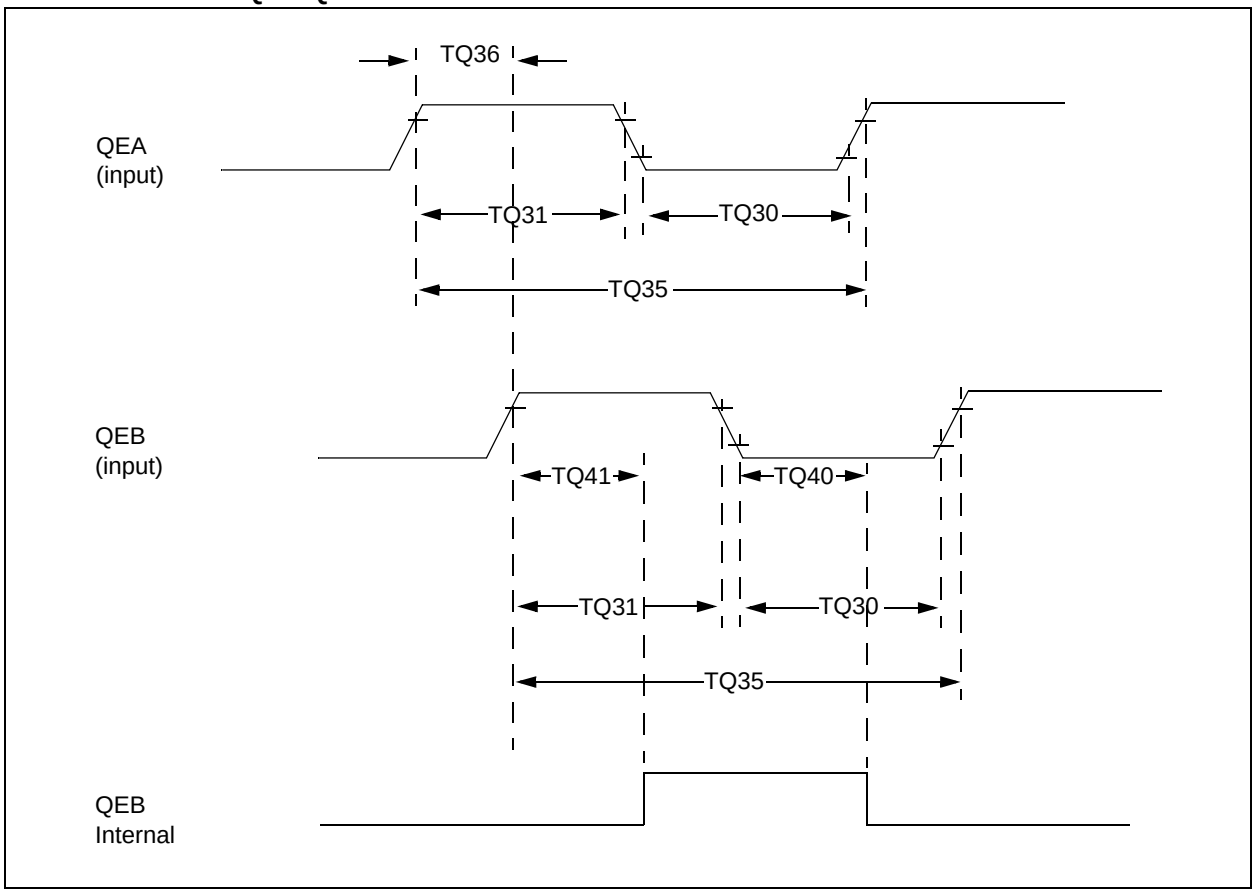


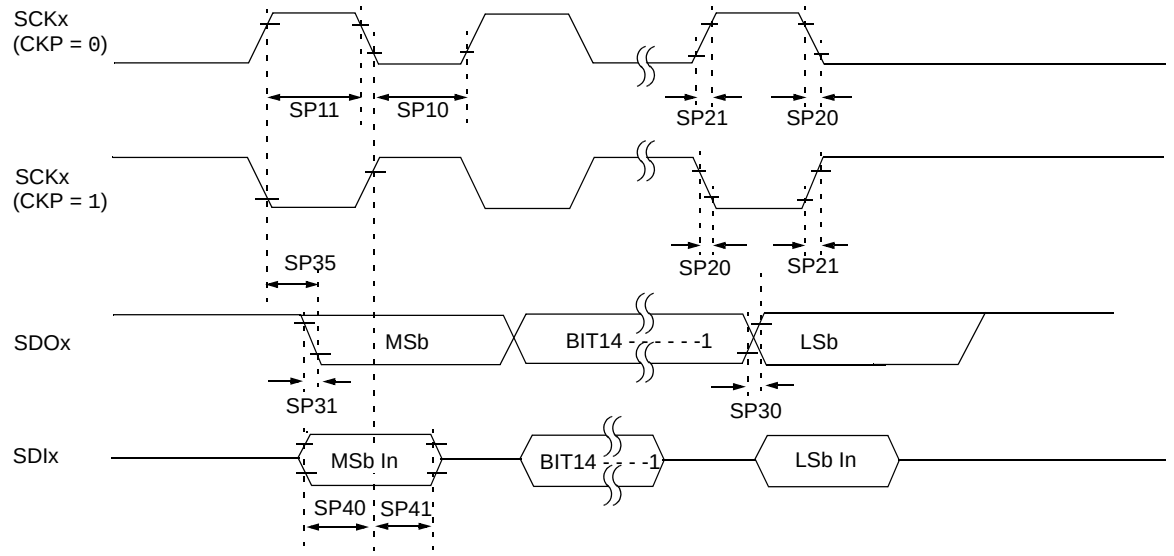
TABLE 23-30: QUADRATURE DECODER TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**	**Typ(2)**	**Max**	**Units**	**Conditions**
TQ30	TQUL	Quadrature Input Low Time	6 TCY	—	ns	
TQ31	TQUH	Quadrature Input High Time	6 TCY	—	ns	
TQ35	TQUIN	Quadrature Input Period	12 TCY	—	ns	
TQ36	TQUP	Quadrature Phase Period	3 TCY	—	ns	
TQ40	TQUFL	Filter Time to Recognize Low, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**
TQ41	TQUFH	Filter Time to Recognize High, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**

Note 1: These parameters are characterized but not tested in manufacturing.

2: N = Index Channel Digital Filter Clock Divide Select bits. Refer to **Section 16. "Quadrature Encoder Interface (QEI)"** in the*"dsPIC30F Family Reference Manual"* (DS70046).

FIGURE 23-16: SPI MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 23-2 for load conditions.

TABLE 23-32: SPI MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time(2)	TCY/2	—	—	ns	
SP11	TscH	SCKx Output High Time(2)	TCY/2	—	—	ns	
SP20	TscF	SCKx Output Fall Time(3)	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time(3)	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time(3)	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time(3)	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.
2: The minimum clock period for SCKx is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.
3: Assumes 50 pF load on all SPI pins.

TABLE 23-34: SPI MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time	30	—	—	ns	
SP71	TscH	SCKx Input High Time	30	—	—	ns	
SP72	TscF	SCKx Input Fall Time(3)	—	10	25	ns	
SP73	TscR	SCKx Input Rise Time(3)	—	10	25	ns	
SP30	TdoF	SDOx Data Output Fall Time(3)	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time(3)	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$↓ to SCKx↑ or SCKx↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$↑ to SDOx Output High-Impedance(3)	10	—	50	ns	
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: Assumes 50 pF load on all SPI pins.

TABLE 23-35: SPI MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time	30	—	—	ns	
SP71	TscH	SCKx Input High Time	30	—	—	ns	
SP72	TscF	SCKx Input Fall Time(3)	—	10	25	ns	
SP73	TscR	SCKx Input Rise Time(3)	—	10	25	ns	
SP30	TdoF	SDOx Data Output Fall Time(3)	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time(3)	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}\downarrow$ to SCKx$\downarrow$ or SCKx$\uparrow$ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}\uparrow$ to SDOx Output High-Impedance(4)	10	—	50	ns	
SP52	TscH2ssH TscL2ssH	$\overline{SSx}\uparrow$ after SCKx Edge	1.5 TCY + 40	—	—	ns	
SP60	TssL2doV	$\overline{SDO}$x Data Output Valid after $\overline{SSx}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCx is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI pins.

TABLE 23-36: I²C™ BUS DATA TIMING REQUIREMENTS (MASTER MODE)

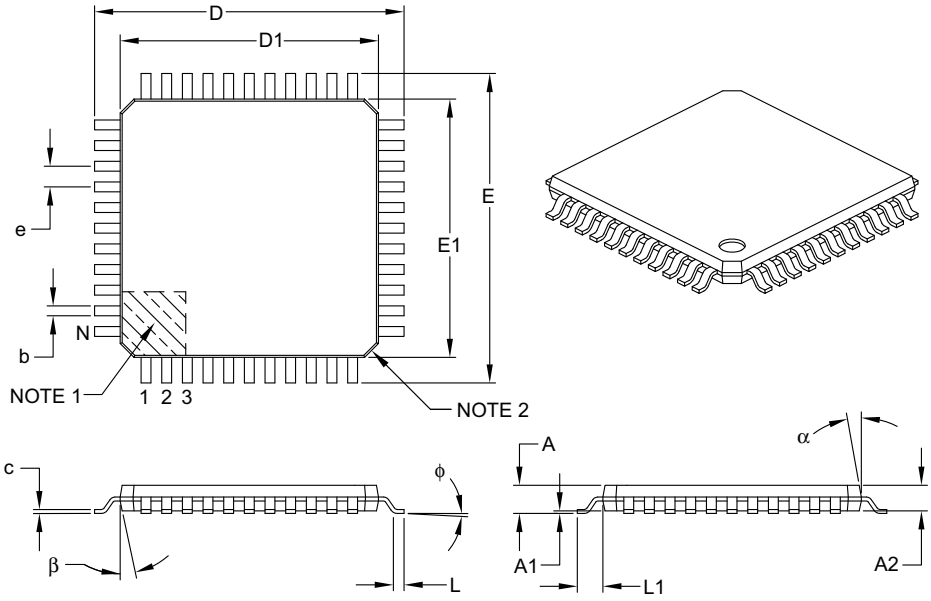
AC CHARACTERISTICS				Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM20	TF:SCL	SDA and SCL Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	—	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	—	—	ns	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(2)	—	—	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	—	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	

Note 1: BRG is the value of the I²C™ Baud Rate Generator. Refer to **Section 21. "Inter-Integrated Circuit (I²C)"** in the*"dsPIC30F Family Reference Manual"* (DS70046).

2: Maximum pin capacitance = 10 pF for all I²C pins (for 1 MHz mode only).

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

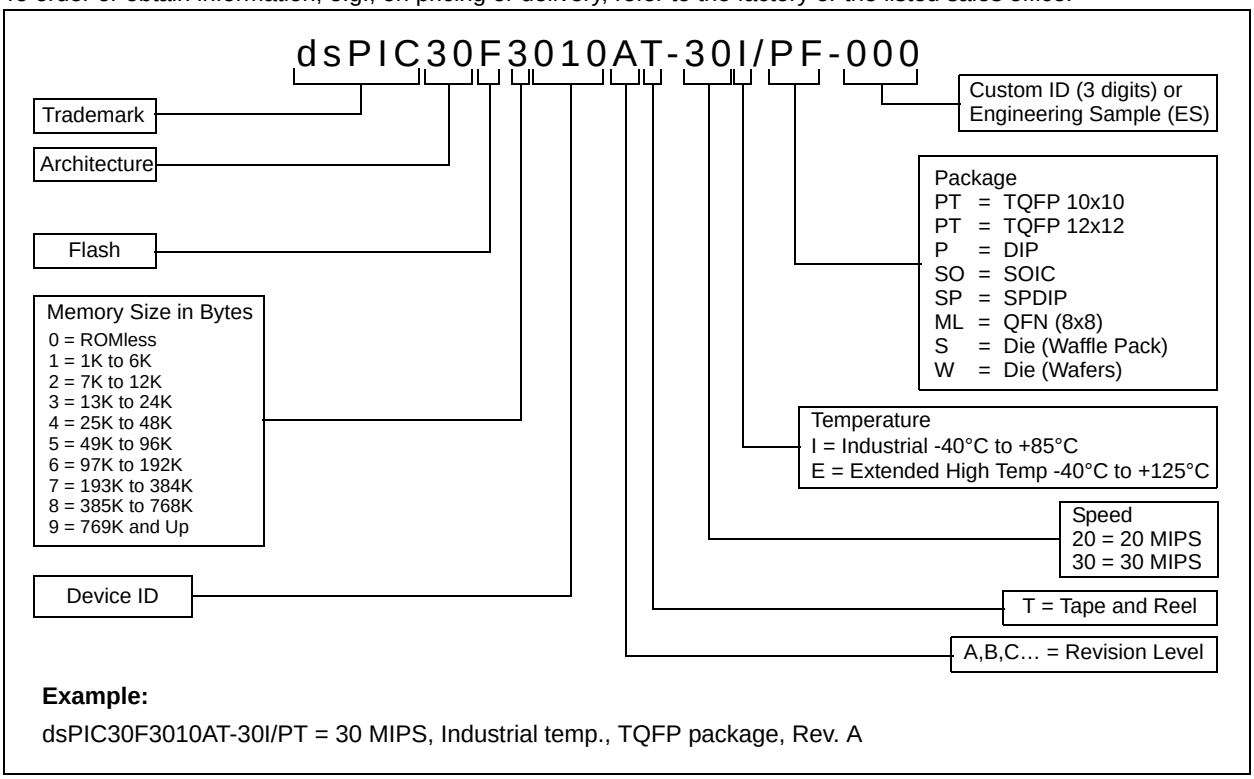
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Example:

dsPIC30F3010AT-30I/PT = 30 MIPS, Industrial temp., TQFP package, Rev. A